

Maintenance Manual

**System Control/Synthesizer Board
CMC-551A/B
MLSL161 & MLSL261
Two-Way Mobile Radio Combinations**

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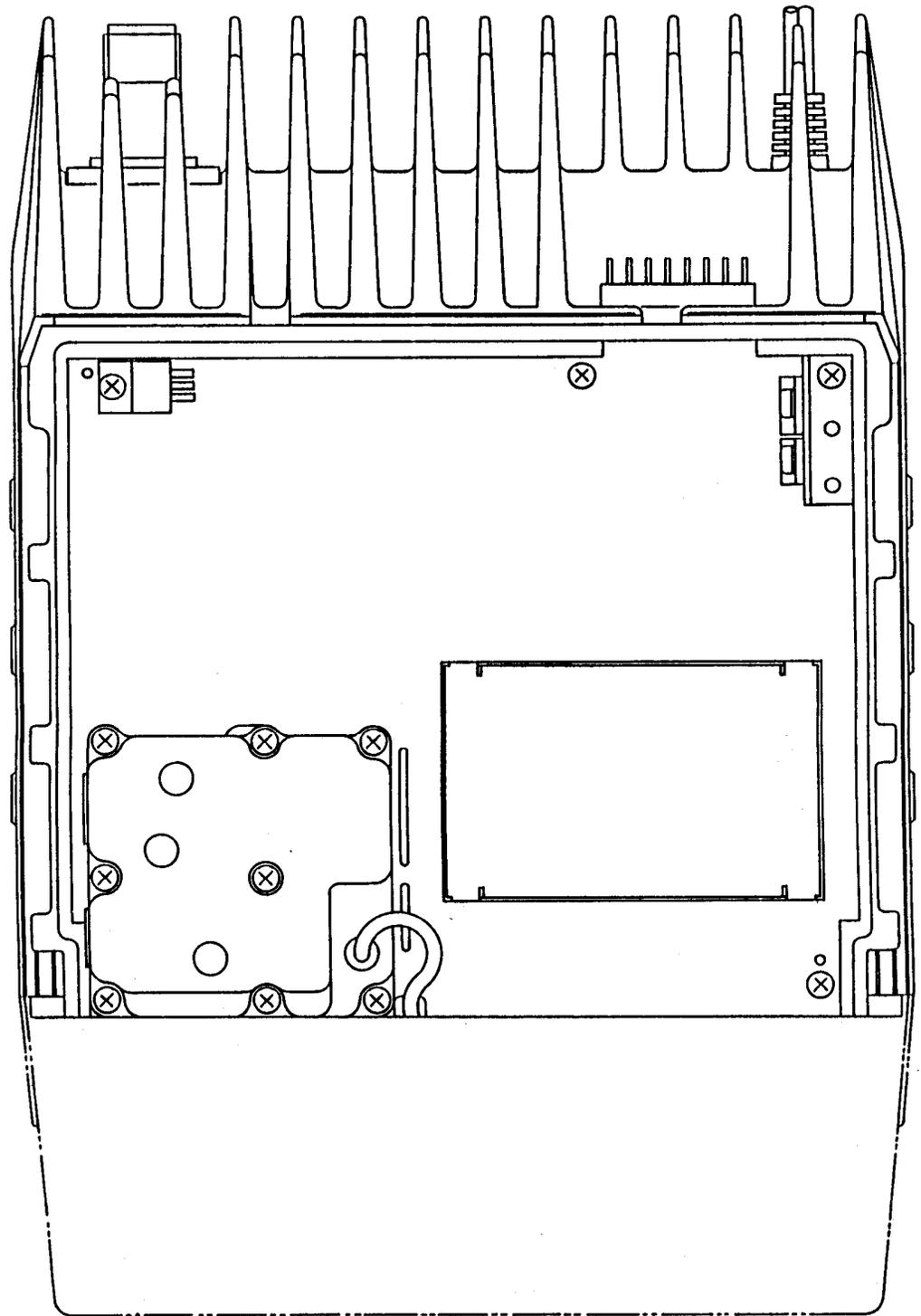
1 DESCRIPTION

The System Control/Synthesizer Board (A801) for the MSL161/261 two way mobile FM radio, controls the radio by providing all necessary digital processing, tones and control functions. The logic circuitry of this board controls channel acquisition, RF frequency selection, tone generation and detection, timing functions and operator interface functions. Interface functions include control panel displays and switch panel controls, microphone hookswitch and programming functions. The frequency synthesizer generates the transmitter output frequency and the receiver first mixer injection frequency. The System Control/Synthesizer Board contains the following:

- Microprocessor
- External memory EPROM for the microprocessor
- The programmable personality EEPROM
- Transmit and receive audio processing circuitry

The System Control/Synthesizer Board (CMC-551) mounts in the top section of the frame assembly as shown in Figure 1.1 – System Control/Synthesizer Location (Top View).

System Control/Synthesizer Board CMC-551 provides the microprocessor, control logic and the audio processing for both the Transmitter circuit and the Receiver circuit. This board also provides the synthesizer circuit for generating operating frequencies.



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Figure 1.1 – System Control/Synthesizer Location (Top View)

2 CIRCUIT ANALYSIS

2.1 POWER DISTRIBUTION

A continuous 13.8 Volts supply is applied to the Power Control Circuit IC606.

Pressing in the power-on switch energizes power relay K501. Energizing this relay applies a switched 13.8 Volts to 5-volt and 9-volt regulators IC101, IC207, IC501, IC607, IC608, and IC610. Switched 13.8 Volts is also applied to Audio PA module IC551.

2.1.1 Digital Processing

The digital processing circuitry consists of microprocessor IC701, Octal Latch IC702, EPROM IC703, EEPROM IC704, PIO IC705 and Flip Flop IC707. IC703 is an 8K X 8-Bit EPROM and is used by the microcomputer to control all radio and system functions. Crystal X701 provides the time base to sequence the microcomputer through an internal software program, allowing it to execute the program stored in the program memory (refer to Figure 2.1 – System Control Block Diagram).

EEPROM IC704 contains all data unique to the radio and is referred to as the “Personality” PROM. Information stored in the Personality PROM includes data for RF channels and Channel Guard as well as all radio options (e.g. carrier control timer, etc.).

2.2 OPERATION

2.2.1 Octal Latch IC702

Octal Latch IC702 is used to exchange data passing between microprocessor IC701 and the memory and control circuits respectively.

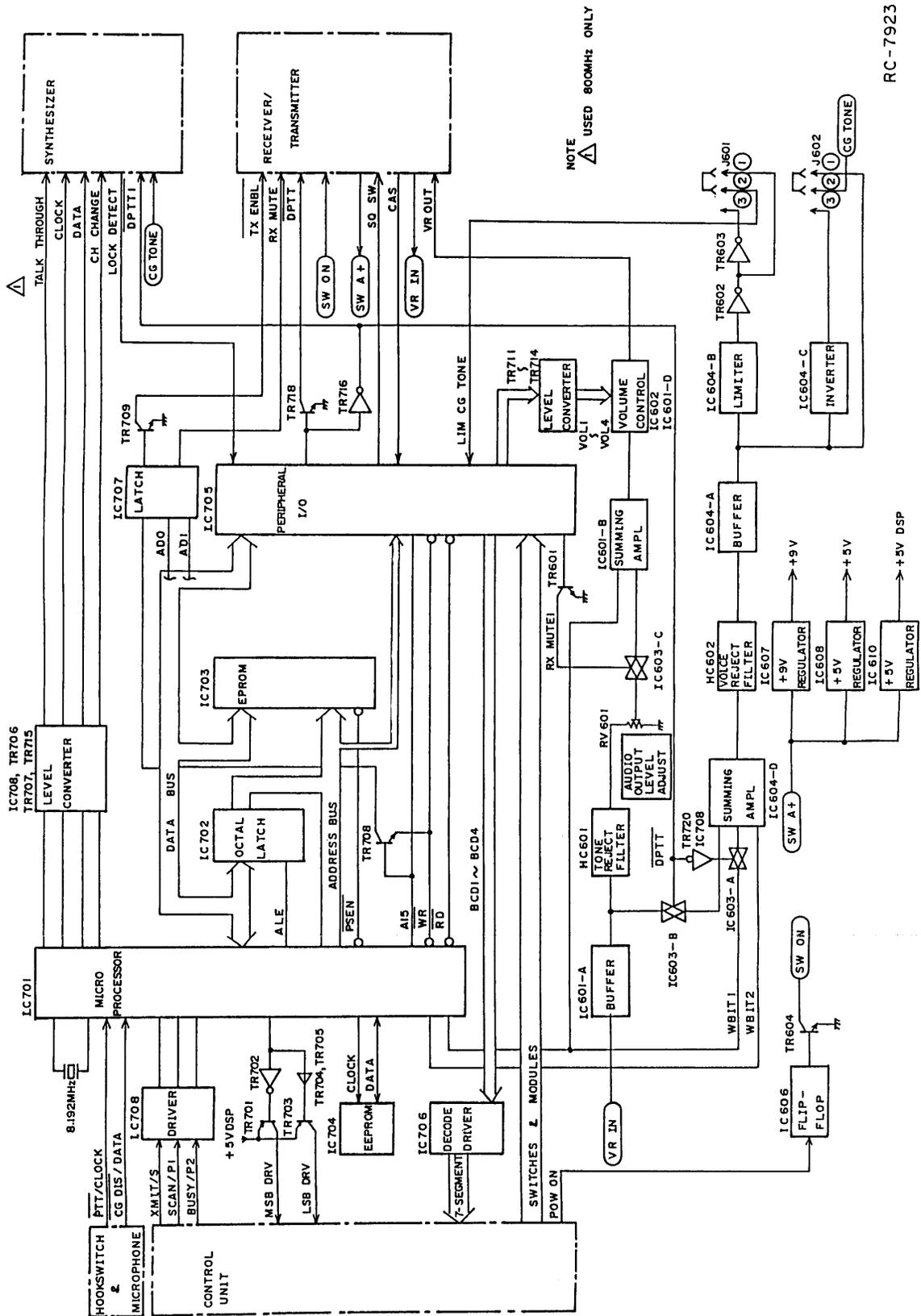
Octal Latch IC702 has the “G” input connected to the Address Latch Enable (ALE) output of the microprocessor to provide a latched address interface between the microprocessor and program memory IC703.

2.2.2 Reset

A reset circuit is provided to reset the microprocessor (IC701), PIO (IC705), and Flip Flop (IC707). The reset is provided by IC609. When SW A+ falls below approximately 9 volts, IC609-3 goes high.

2.2.3 Microprocessor

Microprocessor IC701 directly interfaces with and controls the operation of all the digital processing circuitry. It also interfaces with the radio and control panel functions through PIO IC705. Microprocessor IC701 responds to manual initiated functions of Push-To-Talk (PTT), frequency selection (ADD, DELETE), MONITOR, VOLUME and SCAN ADD and DELETE through PIO IC705. Other functions are performed automatically by the microprocessor.



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Figure 2.1 – System Control Block Diagram

The Microprocessor controls the operation of the radio by performing the following major functions:

- System Timing
- Frequency Selection
- Receiver Scan (16 Channels)
- Two-Channel Priority
- Channel Guard Generation and Detection
- Transmit/Receive Control
- Front Panel Controls and Displays
- Audio Routing and Mute Control

Microprocessor IC701 is sequenced through its program by an internal 8.192 MHz oscillator controlled by crystal X701. The microprocessor accesses its program from EPROM IC703. Reading of the stored program at IC703 occurs when the $\overline{\text{PSEN}}$ line of IC701 is low. The upper eight address lines of IC701 (A8 through A15) are stationary during this access time. The lower eight address lines of IC701 (AD0 through AD7) are captured by Octal Latch IC702 and held stationary. ALE (IC701-27) is used to latch the lower eight address lines. The output of IC703 is then read into the data bus (AD0 through AD7) of IC701.

The microprocessor interfaces with the microphone through MIC PTT and LOGIC HKSW. It also interfaces with PC Programmer through HKSW, MIC PTT, and with Personality EEPROM IC704. The microprocessor control signals include the following:

$\overline{\text{EA}}$	- When this enable line is Low, allows the microcomputer to retrieve all instructions from external memory.
RST	- Resets the microcomputer to beginning of the software program when switched A+ is turned on, immediately following power interruptions or with low battery voltage.
SYN DATA	- Data transferred to synthesizer representing RF frequencies
SYN CLOCK	- Timing output to synthesizer.
SYN LOCK	- A status input signal from the synthesizer to indicate frequency lock status of VCO.
RX MUTE	- Receiver Mute turns receiver audio off while operating in the trunked mode during channel acquisition (idle and wait mode) and when transmitting.
$\overline{\text{DPTT}}$	- Delayed PTT energizes the antenna relay. $\overline{\text{DPTT}}$ low switches off the bilateral audio gates on the System Control/Synthesizer Board in the transmit mode.

- | | |
|-----------------------------|---|
| $\overline{\text{TX ENBL}}$ | - $\overline{\text{TX ENBL}}$ low turns transistor TR103 on and applies 9 volts to the exciter. |
| $\overline{\text{MIC PTT}}$ | - The microprocessor monitors the status of the switched PTT lead from the microphone. It also receives data on this line while the radio is being programmed. |
| $\overline{\text{RD, WR}}$ | - Read, Write allows the microprocessor to read/write data to/from PIO IC705 and write to Flip Flop IC707. |
| $\overline{\text{PSEN}}$ | - Program Send Enable allows the processor to read instructions from program memory IC703. |
| ALE | - Address Latch Enable allows the microcomputer to hold the eight least significant lines (AD0 through AD7) stable by using octal latch IC702. This is necessary when reading from program memory IC703 or reading/writing from/to PIO IC705. |
| A8 – A15 | - Eight most significant address lines. These lines are used to address and access program memory IC703 and PIO IC705. |

2.2.4 Push-To-Talk

Pressing the PTT switch on the microphone applies a ground through J701-2 on the System Control/Synthesizer Board to microprocessor IC701. The ground on IC701-5 causes the $\overline{\text{TX ENBL}}$ output at TR709 to go low and the RX MUTE output at IC707-9 to go high.

The high output of IC705-36 is applied to the input of inverter transistors TR716, TR718, and TR720. The low output at TR720 becomes the high output $\overline{\text{DPTT}}$ through inverter IC708. $\overline{\text{DPTT1}}$, $\overline{\text{DPTT}}$ and DPTT are applied to the synthesizer, Transmitter/Receiver board and the audio circuitry. The low output at TR718 is applied to the Transmitter/Receiver board from J703-13 and operates antenna relay K1. The $\overline{\text{DPTT1}}$ output is supplied to the synthesizer circuit to turn the RX VCO off and TX VCO on. Also the low $\overline{\text{DPTT1}}$ output at TR716 is added to the bilateral switch IC603 in the audio circuit to change the operating mode from receive to transmit. $\overline{\text{TX ENBL}}$ is low and through J703-12 is connected to the Transmitter/Receiver board to apply 9 volts to the exciter and key the transmit circuit.

2.2.5 Channel Select

When a channel is selected and the bit stream is loaded into the synthesizer, a strobe pulse is applied to the Phase-Lock-Loop (PLL) module to allow the synthesizer to generate the correct RF frequency. The microprocessor immediately begins monitoring the LOCK DET LINED to verify that the synthesizer is “on” frequency. If the synthesizer is not locked on the correct frequency, a high on the LOCK DET line (IC705-11) will cause the microprocessor to reload the synthesizer in an attempt to lock it on

frequency. If the synthesizer is locked on the correct frequency and MIC PTT is low, the microprocessor applies the high to the input of inverter transistor TR709. The low output of TR709 (TX ENBL) is connected to the Transmitter/Receiver board through J703-12 to key the transmit circuit.

2.2.6 Monitor

Pressing the MONITOR push-button applies a low to the microprocessor through PIO IC705-19. This low causes the microprocessor to open the receiver so the channel can be monitored.

2.2.7 Channel Guard

In the encode mode, the microprocessor selects the assigned Channel Guard tone/code information from the EEPROM memory for each transmit and receive channel and generate the Channel Guard signal. This signal is applied as Walsh Bits “1” and “2” to summing amplifier IC604-D. These two bits are summed together and filtered to provide a smooth sine wave for Tone Channel Guard.

The output of IC604-D is applied to low-pass filter (Voice Reject) HC602. This filter shunts all frequencies above 300 Hz to ground, preventing those frequencies from interfering with the encoded signal.

In the decode mode, the $\overline{\text{DPTT1}}$ input to bilateral switches IC603-B is high, changing the switches to the receive mode. Audio and tone from VR IN at J703-11 is applied to low-pass filter (Voice Reject) HC602 through buffer amplifier IC604-A. This signal is filtered and only the Channel Guard (if present) is applied to hard limiter IC604-B.

The square-wave output of IC604-B is connected to transistor switch TR602 and the Channel Guard tone is applied to the microprocessor for comparison to determine if the Channel Guard tone is correct. If the tone is correct, the microprocessor causes the RX MUTE line to go low at IC707-9, turning the receiver audio on so that the message can be heard in the speaker.

2.2.8 Carrier Control Timer

The Carrier Control Timer (CTT) is contained in and controlled by the microcomputer. Each time the PTT switch is activated an internal counter begins to count down. If the counter times out, a 500 Hz tone is heard in the speaker for five (5) seconds or until the microphone PTT is released. The timing cycle is programmable from 30 seconds to 7.5 minutes in 30-second increments.

2.2.9 Audio Circuitry

Transmit and receiver audio signals are routed through three-stage bilateral switches IC603-C. The switches are controlled by the RX MUTE 1 output of microprocessor IC701. In the transmit mode, the RX MUTE 1 from IC705-38 is high, TR601 turns on, bilateral switch IC603 control lead is low, switching the stages to the transmit mode as shown on the System Control/Synthesizer Board Schematic Diagram. When the PTT switch is released, the switches revert back to the normal receive mode ($\overline{\text{DPTT1}}$ high).

2.2.10 Transmit Audio

Audio from the microphone at J701-3, 4 (MIC HI, LO) is coupled through capacitor C258 and Audio Processor IC208-B and applied to a high-pass filter. The filter output is coupled through capacitor C230 and Modulation Adjust potentiometer RV201 to the next stage.

The Channel Guard tone/code (if present) from Voice Reject Filter HC602 is coupled through bilateral switch IC604-A and applied to the CG Tone input of Channel Guard Deviation Adjust potentiometer RV202. The Channel Guard tones and audio are combined and applied to summing amplifier IC208-A.

2.2.11 Receive Audio

In the receive mode, the PTT input to the System Control/Synthesizer Board goes high, switching antenna relay to the receive mode. The RX MUTE lead remains low, keeping the audio amplifier turned on.

If the channel being received has been programmed for Channel Guard, the received CG tone is coupled through bilateral switch IC603-B and summing amplifier IC604-D to low-pass filter (Voice Rejection) HC602. The filtered tone output is coupled through IC604-A, limiter IC604-B and transistor TR602 to the microprocessor.

Received audio from the receiver is applied to the input of buffer amplifier IC601-A. The audio out from IC601-A is applied to the volume control circuit (IC602 and IC601-D) through tone reject filter HC601, audio gate IC603-C and audio pre-amplifier IC601-B. The audio output from the volume control circuit is applied through the de-emphasis network, consisting of resistors R551 and R552 and Capacitors C552 and C553, to audio amplifier IC551 which provides up to 4 watts of audio output power to 4 ohm speaker SP801, located in the front panel.

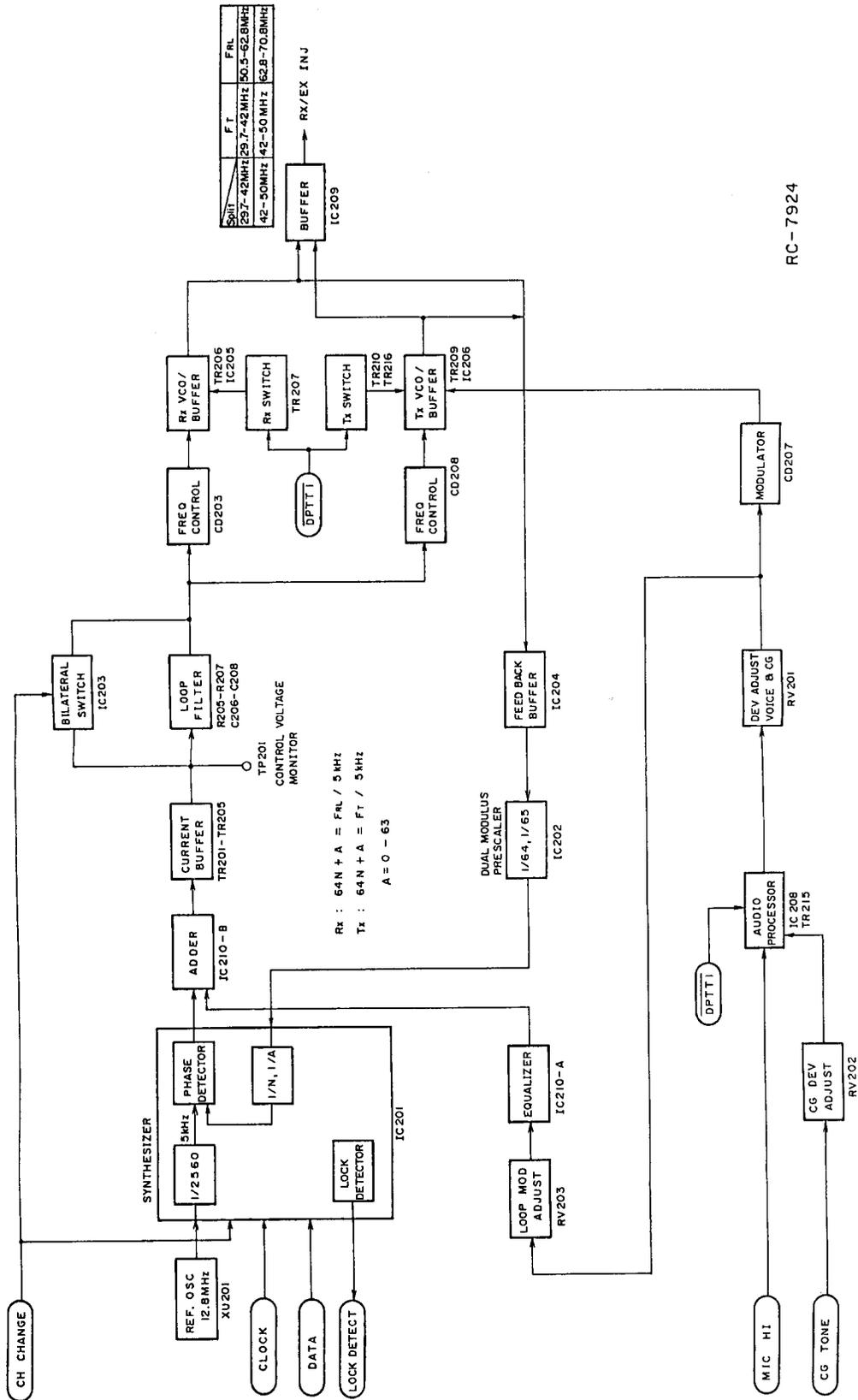
When the radio is squelched, the Carrier Activity Sensor (CAS) signal to the microprocessor through J703-10 goes low. The FLIP FLOP and PIO outputs the RX MUTE and RX MUTE 1 signals. The RX MUTE 1 signal turns bilateral switch IC603-C off and mutes the audio signal. The RX MUTE signal turns transistor TR551 off and mutes the audio signal from IC601-D.

2.2.12 Frequency Synthesizer

The frequency synthesizer circuit consists of reference oscillator XU201, synthesizer chip IC201, dual modulus prescaler IC202, TX and RX Voltage-Controlled Oscillators (VCO's), transistors TR206 and TR209, a loop filter and associated circuitry (refer to Figure 2.2 – Synthesizer Block Diagram).

2.3 REFERENCE OSCILLATOR

Reference oscillator XU201 operates at a frequency of 12.8 MHz and is temperature compensated to provide a frequency stability of ± 5 PPM. Voltage for the oscillator is supplied by 9-volt regulator IC207 and 4-volt zener diode CD201. The oscillator output is applied to synthesizer chip IC201-2 (refer to Figure 2.3 – Synthesizer IC201).



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Figure 2.2 – Synthesizer Block Diagram

2.4 SYNTHESIZER

Synthesizer IC201 consists of a programmable reference oscillator divider ($\div R$), phase detector and programmable VCO dividers ($\div N$, A).

When the PTT switch is pressed (transmit) or released (receive) new frequency data is received on the clock, data and enable lines and the synthesizer immediately begins generating the new RF frequency. This serial data determines the VCO frequency by setting the internal dividers. The reference oscillator frequency applied to the programmable reference oscillator divider is divided down to some lower frequency as indicated by the input data and applied to the internal phase detector. The phase detector compares this signal with the output of the internal programmable VCO dividers. The output of the programmable VCO dividers is a function of the RF frequency which is divided down by the dual modulus prescaler and the programmable VCO dividers. When operating on the correct frequency, the inputs to the phase detector are identical and the output voltage of the phase detector is constant. Under these conditions, the VCO is stabilized or locked on frequency.

If the compare frequencies (phases) differ, an error voltage is generated and applied to the VCO through the frequency acquisition circuit, causing the Phase-Lock-Loop (PLL) to acquire the new frequency.

The LOCK DETECT (LD) line provides the PLL lock status information to the microcomputer. The LOCK DETECT lead is negative going pulses when the PLL is out of lock. When locked on frequency the lead is high.

2.4.1 Equalizer

The equalizer; consisting of IC210-A, R277, R278 and C284; receives transmit audio from Loop Mod adjuster RV203. The output of the equalizer is summed with the output signal from the phase-detector by adder IC210-B.

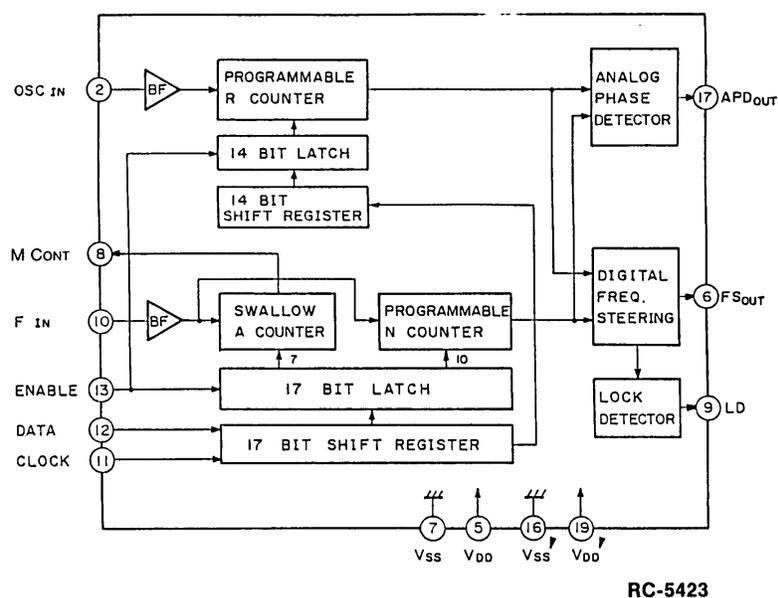


Figure 2.3 – Synthesizer IC201

2.4.2 DC Offset and High Current Buffers

DC offset buffers TR205, TR204 and diode CD204 receive the error voltage from the synthesizer and increases this level by 1.8 VDC to extend the operating range of the high current buffers. When the PLL is off frequency due to a channel change or frequency drift, the error voltage from the synthesizer (APD) rises or falls, turning TR202 either on or off. TR202 controls the DC offset buffer TR205. R204, CD204 and TR205 complete a high current rapid charge or discharge path for C206-C208.

As the error voltage decreases, TR202, TR205 and CD204 turn on, completing a discharge path for C206-C208 through bilateral switches IC203. When the error voltage goes positive, TR202, TR205 and CD204 are turned off, allowing C206-C208 to charge through R204. IC203 is turned on for 15 milliseconds each time a channel is changed in receive or when changing from transmit to receive. The time is 15 milliseconds when in transmit.

2.4.3 Loop Filter

The loop filter consists of R205-R207, and C206-C208. This filter controls the bandwidth and stability of the synthesizer loop. Bilateral switch IC203 is controlled by the 15 milliseconds, 9-volt channel change pulse. When the channel change pulse is present, the bilateral switch shorts out the low pass filter, greatly increasing the loop bandwidth to achieve the 35 milliseconds channel acquisition time required for PSLM. The low pass filter removes noise and other extraneous signals internal to the synthesizer chip.

The output of the filter is applied to the varicaps in the transmit and receive VCO's to adjust or correct the VCO frequency.

2.4.4 Receiver VCO

The Receiver VCO consists of a low noise JFET oscillator, TR206, followed by high gain buffer IC205. This buffer prevents external loading and improves power gain. The VCO is a Colpitts oscillator with the varicap capacitors and inductor forming the tank circuit. Capacitor CV201 allows manual adjustment of the VCO across the frequency split. The varicap provides voltage controlled frequency adjustment of about 1 MHz. The VCO is switched on and off under control of the DPTT1 line. When the DPTT1 line is high, the Receiver VCO is turned on (TR207 is on). The RX injection output is typically +4 dBm. RX VCO lock time is 15 milliseconds maximum.

2.4.5 Transmitter VCO

The transmitter VCO is basically the same as the Receiver VCO. The varicap provides a voltage controlled adjustment range of approximately 1 MHz. The EX injection provides a typical output of +4 dBm. Transmit audio is applied to modulation adjustment control RV201. Deviation is set for ± 4.5 kHz. TX VCO lock time is 15 milliseconds maximum.

The transmitter VCO is turned on when $\overline{\text{DPTT1}}$ line is low (TR210 is on, TR216 is off).

The use of two VCO's allows rapid independent selection of transmit and receive frequencies across the frequency split.

2.4.6 VCO Characteristics

The synthesizer has two VCO's, the frequency of which is directly related to a control voltage generated by the synthesizer circuitry and must remain within specified limits for the synthesizer to function properly. The RX VCO typically will increase in frequency about 1 MHz when the control voltage moves from its lower limit to its upper limit. The TX VCO moves about 1 MHz for the same situation. By tuning the variable capacitor in the RX VCO and coil in the TX VCO, the same control voltage frequency spread can be moved up or down through the full range of frequencies that the radio operates on.

In order to maintain the selectivity, hum and noise performance of the radio, the frequency range that the VCO's can be voltage tuned must be kept to a minimum. This requires that all the available voltage range be fully utilized. The alignment procedure, therefore, instructs the user to accurately set the control voltage to the upper limit of the voltage range at the highest or lowest frequency channel.



Going too high with the voltage setting at the highest frequency channel may cause problems over temperature extremes as the VCO's will drift slightly. Set the voltage too low and you may not remain within the required lower voltage limit as you cover the radio's maximum two frequency spread.

If the required frequency spread is less than the maximum two frequency spread, then there are no restrictions on setting the lowest and highest frequencies within the required voltage limits.

The minimum tuning requirement of the VCO's is to cover the proper frequency range. For instance, to cover 45 to 46 MHz, the VCO must be tunable such that at 46 MHz, the control voltage is equal to the upper voltage limit, and at 45 MHz the voltage must be greater than the lower limit. If the control voltage can be tuned higher than the lower limit at 45 MHz, this simply means that you can program channels below 45 MHz until you finally run into the lower voltage limit. When tuning the VCO's to a channel close to 46 MHz, the control voltage may not reach the upper control voltage limit. This is normal for some radios and is due to the tolerances on the many capacitors in the VCO. Even though it takes very little change in capacitance to shift the VCO frequency range a few megahertz, this variation has been carefully compensated for by increased tuning range for the VCO. Therefore, if you tune to 50 MHz, you may not achieve the maximum control voltage for all radios, but you will always be greater than the lower voltage limit.

2.4.7 Feedback Buffer

The buffered output of the RX VCO and TX VCO are supplied to the receiver mixer and the exciter respectively and to the feedback buffer. Buffering is provided by IC204 and the output applied to dual modulus prescaler IC202.

2.4.8 Dual Modulus PreScaler

The dual modulus prescaler completes the PLL feedback path from the synthesizer to loop filter, to the VCO's and feedback buffer and then back to the synthesizer through the prescaler. The prescaler divides the VCO frequency by 64 or 65 under control of M Cont

from the synthesizer. The output of the prescaler is applied to the synthesizer where it is divided down to 5 kHz by an internal $\div N$, $\div A$ counter and compared in frequency and phase with the divided down frequency from the reference oscillator. The result of this comparison is the error voltage used to maintain frequency lock. The N, A counter is controlled by data received from the microcomputer. Depending on the operating frequency, the DC voltage at TP201 should be within the range 3.5 and 7.5 VDC when the PLL is locked.

2.4.9 Audio Processor

The audio processor provides audio pre-emphasis with amplitude limiting and post limiter filtering and a total gain of approximately 27 dB. Approximately 30 dB gain is provided by IC208B and 4 dB by IC208A and -7 dB by R248, R249.

The 9-volt regulator IC207 powers the audio processor and applies regulated 9 volts to a voltage divider consisting of R245 and R246. The +4.7 volts output from the voltage divider establishes the operating reference point for operational amplifiers IC208B and IC208A. C261 provides an AC ground at the summing input of both operational amplifiers.

When the input signal to IC208B-6 is of a magnitude such that the amplifier output at IC208B-7 does not exceed 5 volts pp, the amplifier provides a nominal 30 dB gain. When the audio signal level at IC208B-7 exceeds 5 volts pp, the amplifier gain is reduced to 1. This limits the audio amplitude at IC208B-7 to 6 volts pp.

Resistors R242, R243 and Capacitor C258 comprise the audio pre-emphasis network that enhances the signal-to-noise ratio. R243 and C258 control the pre-emphasis curve below limiting. R242 and C258 control the cut-off point for high frequency pre-emphasis.

Audio from the microphone is coupled to the audio processor through R242 and C258.

The amplified output of IC208B is coupled through R248, R250, R252, and R253 to a second operational amplifier IC208A. TR215 is controlled by the DPTT1 line so that TX audio is transmitted only when the PTT switch is pressed.

The Channel Guard tone input is applied to IC208A-2 through CG DEV Adjust RV202, C263 and R254. The CG tone is then combined with the microphone audio at IC208A. IC208A provides a signal gain of approximately 4 dB.

A post limiter filter consisting of IC208A, R250-R253, C264 and C265 provide 12 dB per octave roll-off. R248 and C260 provide an additional 6 dB per octave roll-off for a total of 18 dB. The output of the post limiter filter is coupled through DEV Adjust RV201 to the transmitter VCO.

Tx enable switch TR215 shorts out operational amplifier IC208-A when the radio is in the receive mode. The DPTT1 signal is generated by the microcomputer when the PTT switch is released and is 9 VDC in the receive mode.

2.4.10 SCAN Operation

The scan operation is controlled by the microprocessor, and provides for scanning any or all of up to 16 channels. The scanned channels may be located anywhere within the frequency band of the radio, and can include two priority channels (P1 and P2).

If desired, all 16 channels can be scanned with or without priority level. When SCAN is enabled, scanning of the selected channels starts immediately. Scan time is approximately 50 to 450 milliseconds per channel, depending upon whether Channel Guard has been programmed for a particular scan channel. If a carrier is not detected, the scan time is 50 milliseconds. If a carrier is detected and Channel Guard is programmed for the channel, the time is 200-450 milliseconds, depending upon how close the Channel Guard tone is to the desired tone. Typical value is 250 milliseconds.

Priority 1 (P1) and Priority 2 (P2) channels, if present, are not part of the non-priority channel scan list (S1, S2, S3...) and are treated separately. If there is no activity on any of the scanned channels, then the scan sequence is as shown in the following examples.

Example 1: (More than four non-priority channels, i.e., six channels)

P1-P2-S1-S2-S3-S4-P1-P2-S5-S6-S1-S2-P1-P2-S3-S4-S5-S6-P1-P2-...

Example 2: (Four or less non-priority channels, i.e., three channels)

P1-P2-S1-S2-S3-P1-P2-S1-S2-S3-P1-P2-S1-S2-S3-P1-P2-S1-S2-S3-...

Therefore, the scan sequence is: Scan P1 and P2 if programmed. Then scan up to four non-priority channels before scanning P1 and P2 again. If more than 4 non-priority channels exist, then scan will wrap around, continuously scanning four channels of the non-priority list between each P1, P2 sequence. If the number of non-priority channels is less than or equal to four, then all non-priority channels will be scanned between each P1, P2 scan.

As an added example, consider channels 1-8 to be the scanned channels, with P1 being Channel 1 and P2 being Channel 8. The scanning order then would be:

S1-S2-S3-S4-P1-P2-S5-S6-S1-S2-P1-P2-S3-S4-...

7 6 5 4 1 8 3 2 7 6 1 8 5 4

Since it takes approximately 50 to 450 milliseconds to scan each channel, then each Priority channel is sampled every 0.3 to 2.7 seconds and the Non-Priority channels are sampled at least once every 0.4 to 3.6 seconds. If Channel Guard is programmed for a channel but no carrier is detected, the scan time for that channel is 50 milliseconds.

2.4.10.1 SCANNING (Stopped On A Valid SCAN Channel)

Once a carrier is detected, the Receive Channel display will light up, indicating that channel. If the channel is a Non-Priority channel, and there are no Priority channels, then scanning is halted. If only a Priority 2 (P2) channel is present, then it is scanned every 5 seconds if it has Channel Guard programmed and carrier is detected, and every second otherwise. If there is only a Priority channel, then it is sampled every 2.5 seconds if it has Channel Guard 1 (P1) and carrier is detected, and every 500 milliseconds otherwise. If there are P1 and P2 Priority channels, the sample rate will vary.

In order to show the various scan conditions, the following conditions are used:



The following conditions are shown while listening to a non-priority channel.

CONDITION 1: P1 and P2 have Channel Guard programmed.

a. No carriers detected

P1-P1-P2-P1-P1-P2-P1-P1-P2-...

tb (time between samples) = 500 msec

ts (time of sample) = 100 msec

Note: ts is the whole time placed in the signal being heard.

b. Carrier on P1 detected/wrong Channel Guard

P1-P2-P2-P2-P2-P2-P1-P2-P2-P2-P2-P2-P1-P2-...

tb = 1 second

ts = 100 msec for P2

250-500 msec for P1

c. Carrier on P2 detected/wrong Channel Guard

P1-P2-P1-P1-P1-P1-P1-P1-P1-P1-P2-P1-...

tb = 500 msec

ts = 100 msec for P1

250-500 msec for P2

d. Carrier on P1 and P2 detected/both wrong Channel Guard

P1-P1-P2-P1-P1-P2-P1-P1-P2-...

tb = 2.5 seconds

ts = 250-500 msec

e. Carrier on P1 and right Channel Guard

Stop can, display P1

f. Carrier on P2 and right Channel Guard

Display P2, and scan P1

P1-P1-P1-P1-P1-P1-...

tb = 500 msec

ts = 100 msec

g. Carrier on P2 with right Channel Guard, carrier/wrong Channel Guard P1

P1-P1-P1-P1-P1-...

tb = 2.5 second
ts = 250-500 msec

CONDITION 2: Priority 1 has Channel Guard programmed, PRI2 does not

a. No carriers detected

P1-P1-P2-P1-P1-P2-P1-P1-P2-...

tb (time between samples) = 500 msec
ts (time of sample) = 100 msec

b. Carrier on P1 detected/wrong Channel Guard

P1-P2-P2-P2-P2-P2-P1-P2-P2-P2-P2-P2-P1-P2-...

tb = 1 second
ts = 100 msec for P2
250-500 msec for P1

c. Carrier on P1 detected/right Channel Guard

Stop on P1, stop scan

d. Carrier on P2

Stop on P2, scan P1

P1-P1-P1-P1-...

tb = 500 msec
ts = 100 msec

e. Carrier on P2 and P1 with wrong Channel Guard on P1

Stop on P2, scan P1

P1-P1-P1-P1-P1-P1-...

tb = 2.5 seconds
ts = 250-500 msec

CONDITION 3: P2 has Channel Guard, P1 does not

a. No carriers detected

P1-P1-P2-P1-P1-P2-P1-P1-P2-...

tb (time between samples) = 500 msec
ts (time of sample) = 100 msec

b. Carrier on P2 detected/wrong Channel Guard

P1-P2-P1-P1-P1-P1-P1-P1-P1-P1-P2-P1-...

tb = 500 msec
ts = 100 msec for P1
250-500 msec for P2

c. Carrier on P2 detected/right Channel Guard

Stop on P2, scan P1

P1-P1-P1-P1-P1-P1-...

tb = 500 msec
ts = 100 msec

d. Carrier on P1 detected

Stop on P1, stop scan

CONDITION 4: P1 and P2 with no Channel Guard

a. No carriers detected

P1-P1-P2-P1-P1-P2-P1-P1-P2-...

tb (time between samples) = 500 msec
ts (time of sample) = 100 msec

b. Carrier on P2

Display P2, scan P1

P1-P1-P1-P1-P1-P1-...

tb = 500 msec
ts = 100 msec

c. Carrier on P1

Stop on P1, stop scan

2.4.11 Hang Time

If the carrier on a Non-Priority channel disappears before a carrier is detected on a Priority channel, then a 5-second hang time is applied before Non-Priority scanning is resumed. However, during this time the Priority channels are still being sampled. The hang time is provided to prevent fades from causing big gaps in the audio signals. The transmitter may be keyed at any time during the hang time. The hang time is restarted when the transmitter is unkeyed.

If a carrier (or Channel Guard tone if programmed) is detected on a Priority channel during the sample period, then the channel is immediately switched to the Priority

channel, and either the PRI-1 or PRI-2 indicator will turn on. If the carrier is on Priority 1 channel, scanning is stopped until the carrier goes away (plus the five second hang time). If the carrier is on the P2 channel, then P1 is still sampled every 500 milliseconds if no Channel Guard, and every 2.5 seconds if Channel Guard is programmed. If there is no P1 channel, then scanning is stopped until the carrier disappears (+5 seconds). Once a carrier is detected on the P1 channel, the channel is switched to Priority 1 regardless of what is being received on another channel (Non-Priority or P2).

2.4.12 Other Characteristics

When the microphone is removed from the hookswitch, scanning will stop and revert to the Pre-Scan selected channel if the scan has not stopped on any channel. The scan light will blink. Transmit (if a valid TX frequency is programmed) is possible on the pre-scan channel while off-hook. The channels can be changed during this mode, but when the microphone is returned to the hookswitch, hang time occurs on the pre-scan selected channel.

If a channel has been detected and the radio is hanging on this channel, then scanning stops and the radio will sit on the received scan channel until the microphone is placed on the hook-switch or scan is disabled by pressing the SCAN button. If the microphone is replaced on the hookswitch, scanning will resume five seconds later. Channel changes are allowed until the microphone is replaced in the hookswitch. When scan is disabled, the radio automatically reverts to the Pre-Scan selected channel.

When the PTT is pressed, the channel that the scan was hanging on when the microphone was removed from the hookswitch will be the transmit channel. This is the displayed channel. If the PTT is pressed while on-hook and in SCAN, the transmitter is disabled until scan stops on a valid channel or scan is disabled.

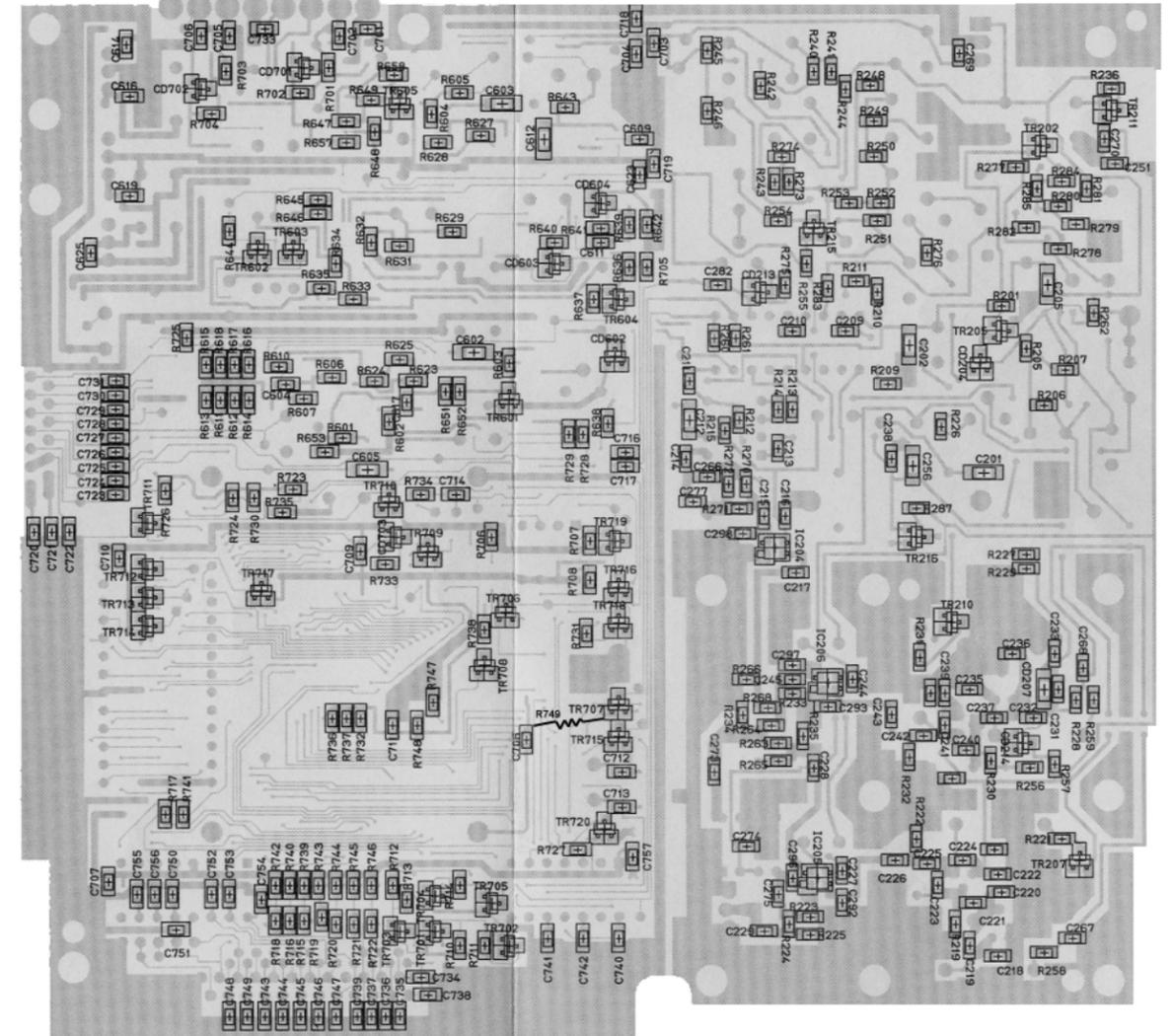
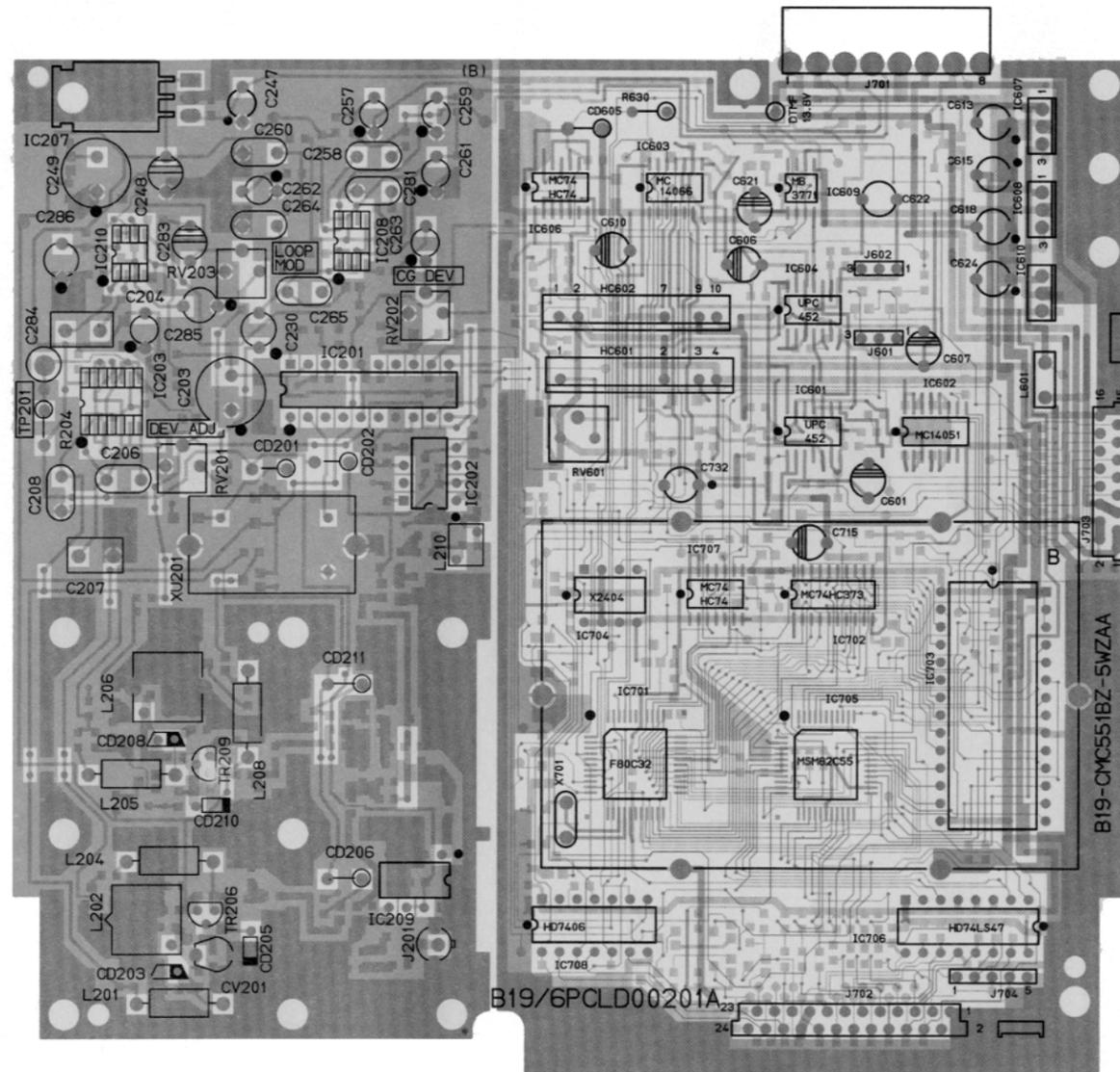
Once stopped on a channel and the microphone removed from the hookswitch, the Channel Guard decode function is disabled until the microphone is returned to the hookswitch.

When in the scan mode and the channel display blinks while displaying a channel number, this indicates that one of the scan channels is not locking on frequency (not properly programmed, radio not properly aligned, etc.). Slowly stepping through the channels with scan disabled will reveal the bad channel because the channel display will blink on the bad channel only.

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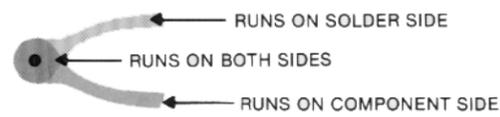
COMPONENT SIDE

SOLDER SIDE

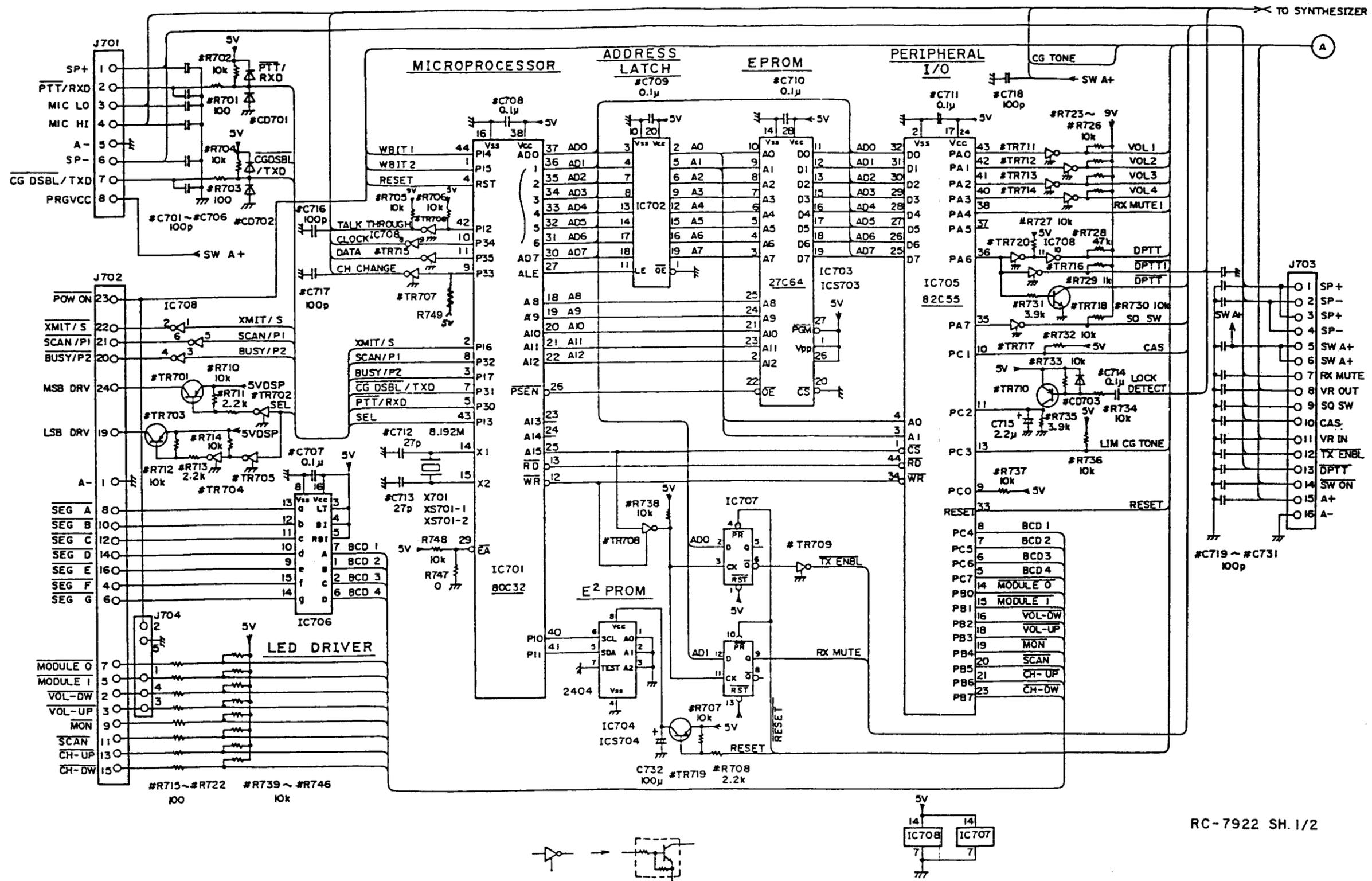


(PCLD00201D)

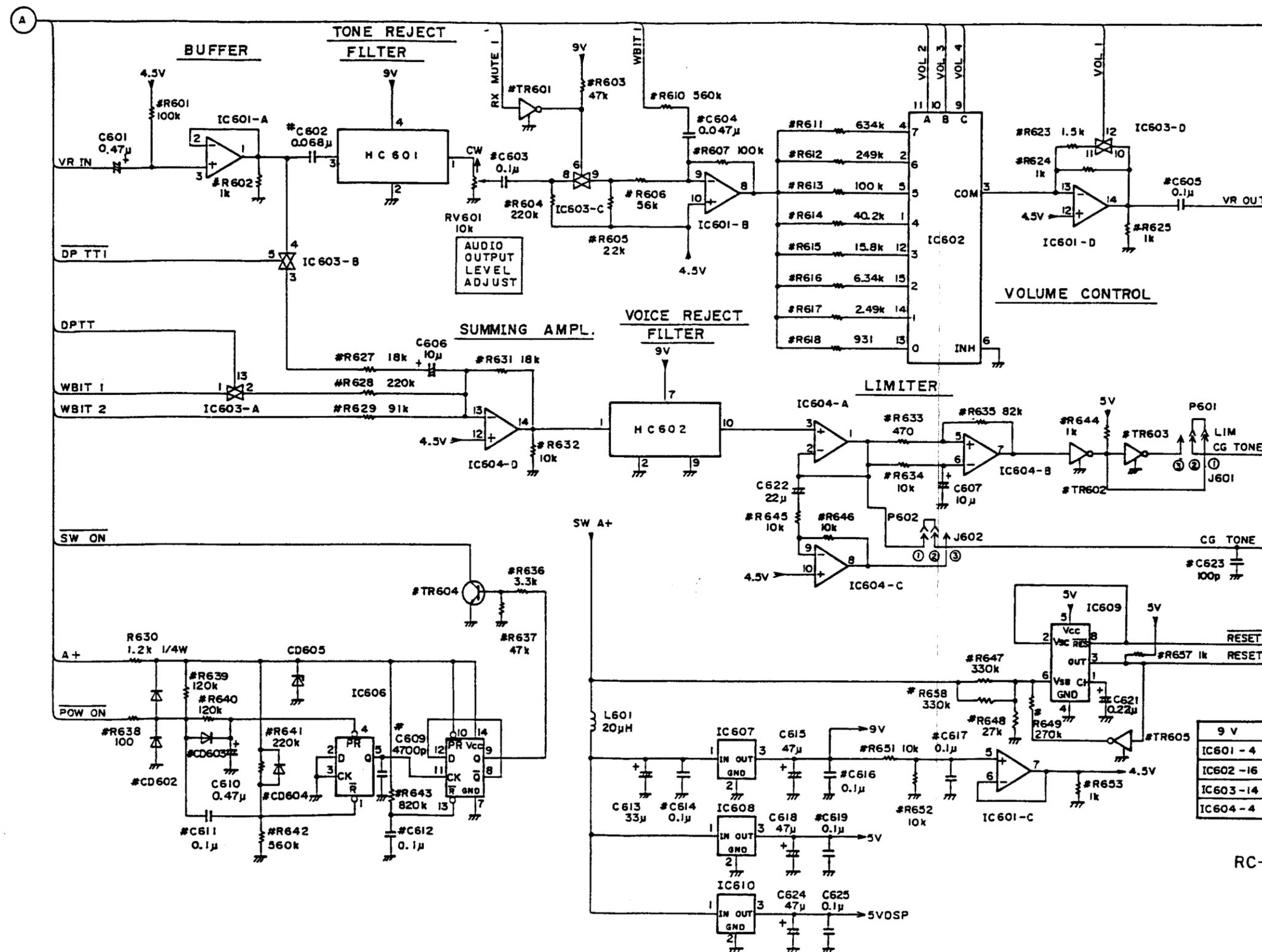
(PCLD00201D)



SCHEMATIC DIAGRAM



RC-7922 SH. 1/2



9 V	GND
IC601 - 4	IC601 - 11
IC602 - 16	IC602 - 7,8
IC603 - 14	IC603 - 7
IC604 - 4	IC604 - 11

RC-7922 SH. 2/2

△ COMPONENT IDENTIFICATION CHART

SPLIT SYMBOL	CMC-551A-2 (29.7-42 MHz)	CMC-551B-2 (42 - 50 MHz)
C219	56 pF	33 pF
C221	56 pF	33 pF
C225	5 pF	3 pF
C232	18 pF	15 pF
C235	.82 pF	33 pF
C237	150 pF	22 pF
C240	33 pF	39 pF
C241	56 pF	47 pF
C242	10 pF	5 pF
C266	33 pF	18 pF
C292	27 pF	0
CV201	50 pF (Max.)	30 pF (Max.)
L205	10 μ H	4.7 μ H
L206	6LALD00002	6LALD00004
L208	10 μ H	1 μ H
L210	6LALD00005	6LALD00006
R210	68 k Ω	12 k Ω
R223	120 Ω	150 Ω
R224	47 Ω	33 Ω
R225	120 Ω	150 Ω
R226	0	4.7 k Ω
R259	0	33 Ω
R276	1 k Ω	0

RC-7920 SH2/2

PARTS LIST

PARTS LIST
SYSTEM CONTROL SECTION
MLS (LOW BAND)
ISSUE 1

SYMBOL	PART NO.	DESCRIPTION
----- CAPACITORS -----		
C601	B19/5CSAC01065	Tantalum: 0.47 uF, ±10%, 35 VDCW.
C602	B19/5CAAD01201	Ceramic: 0.068 uF, ±10%, 25 VDCW, Temp coef ±15%.
C603	B19/5CAAD01237	Ceramic: 0.1 uF, ±10%, 25 VDCW, Temp coef ±15%.
C604	B19/5CAAD01724	Ceramic: 0.047 uF, +80% -20%, 50 VDCW, Temp coef +30%, -80%.
C605	B19/5CAAD01237	Ceramic: 0.1 uF, ±10%, 25 VDCW, Temp coef ±15%.
C606 and C607	B19/5CSAC00932	Tantalum: 10 uF, ±10%, 16 VDCW.
C609	B19/5CAAD00957	Ceramic: 4700 pF ±10%, 50 VDCW, Temp coef ±15%.
C610	B19/5CSAC01065	Tantalum: 0.47 uF, ±10%, 35 VDCW.
C611	B19/5CAAD01078	Ceramic: 0.1 uF +80% -20%, 25 VDCW, Temp coef +30%, -80%.
C612	B19/5CAAD01237	Ceramic: 0.1 uF, ±10%, 25 VDCW, Temp coef ±15%.
C613	B19/5CEAD02283	Electrolytic: 33 uF, ±20%, 25 VDCW.
C614	B19/5CAAD01078	Ceramic: 0.1 uF +80% -20%, 25 VDCW, Temp coef +30%, -80%.
C615	B19/5CEAD00756	Electrolytic: 47 uF, ±20%, 16 VDCW.
C616 and C617	B19/5CAAD01078	Ceramic: 0.1 uF +80% -20%, 25 VDCW, Temp coef +30%, -80%.
C618	B19/5CEAD00756	Electrolytic: 47 uF, ±20%, 16 VDCW.
C619	B19/5CAAD01078	Ceramic: 0.1 uF +80% -20%, 25 VDCW, Temp coef +30%, -80%.
C621	B19/5CSAC00988	Tantalum: 0.22 uF ±10%, 35 VDCW.
C622	B19/5CEAD02733	Electrolytic: 22 uF, ±20%, 16 VDCW.
C623	B19/5CAAD00839	Ceramic: 100 pF ±10%, 50 VDCW, Temp coef ±15%.
C624	B19/5CEAD00756	Electrolytic: 47 uF, ±20%, 16 VDCW.
C625	B19/5CAAD01078	Ceramic: 0.1 uF +80% -20%, 25 VDCW, Temp coef +30%, -80%.
C701 thru C706	B19/5CAAD00839	Ceramic: 100 pF ±10%, 50 VDCW, Temp coef ±15%.
C707 thru C711	B19/5CAAD01078	Ceramic: 0.1 uF +80% -20%, 25 VDCW, Temp coef +30%, -80%.
C712 and C713	B19/5CAAD00952	Ceramic: 27 pF ±5%, 50 VDCW, Temp coef ±15%.
C714	B19/5CAAD01078	Ceramic: 0.1 uF +80% -20%, 25 VDCW, Temp coef +30%, -80%.
C715	B19/5CSAC01069	Tantalum: 2.2 uF, ±10%, 35 VDCW, Temp coef ±15%.
C716 thru C731	B19/5CAAD00839	Ceramic: 100 pF ±10%, 50 VDCW, Temp coef ±15%.
C732	B19/5CEAD01827	Electrolytic: 100 uF, ±20%, 16 VDCW.
----- DIODES -----		
CD602	B19/5TXAD00320	Silicon, fast recovery (2 diodes in series): sim to ISS226.
CD603 and CD604	B19/5TXAD00290	Silicon, fast recovery (2 diodes in series common): sim to TOSHIBA ISS184.
CD605	B19/5TXAE00568	Zener: 5V; sim to HITACHI HZ5C1RE.
CD701 and CD702	B19/5TXAD00320	Silicon, fast recovery (2 diodes in series): sim to ISS226.
CD703	B19/5TXAD00290	Silicon, fast recovery (2 diodes in series common): sim to TOSHIBA ISS184.
----- HYBRID CIRCUIT -----		
HC601	B19/6DHPD00168	Filter: sim to MURATA DHPD168.
HC602	B19/6DHPD00169	Filter: sim to MURATA DHPD169.

SYMBOL	PART NO.	DESCRIPTION
----- INTEGRATED CIRCUITS -----		
IC601	B19/5DAAA00328	Linear, Quad OP Amp: sim to NEC UPC452G2.
IC602	B19/5DAAJ00689	Digital, 8-Channel Analog Multiplexer: sim to MOTOROLA MC14051BF.
IC603	B19/5DAAJ00629	Digital, Bilateral Switch: sim to MC14066BF.
IC604	B19/5DAAA00328	Linear, Quad OP Amp: sim to NEC UPC452G2.
IC606	B19/5DAAJ00688	Digital, DualD-type Flip-Flop: sim to MOTOROLA MC74HC74F.
IC607	B19/5DAAR00021	Linear, positive voltage regulator: sim to MATSUSHITA AN6541.
IC608	B19/5DAAJ00305	Linear, positive voltage regulator: sim to MOTOROLA MC7805CT.
IC609	B19/5DDAT00763	Linear, Voltage Detector: sim to FUJITSU MB3771FP.
IC610	B19/5DAAJ00305	Linear, positive voltage regulator: sim to MOTOROLA MC7805CT.
IC701	B19/5DDEFX00004	Digital, Microcontroller: sim to MATRA HARRIS F-80C32.
IC702	B19/5DAAJ00766	Digital, Octal Transparent Latch: sim to MOTOROLA MC74HC373F.
IC703	B19/5DDAY00366	Digital, EPROM: sim to AMD AM27C64-250DC.
IC704	B19/5DDBY00044	Digital, EEPROM: sim to XICOR X2404.
IC705	B19/5DDAG00274	Digital, PIO: sim to OKI MSM82C55A-2GS.
IC706	B19/5DDAF00390	Digital, BCD to n-Segment Decoder/Driver: sim to HITACHI HD74LS47P.
IC707	B19/5DAAJ00688	Digital, DualD-type Flip-Flop: sim to MOTOROLA MC74HC74F.
IC708	B19/5DDAF00113	Digital, Hex Inverter: sim to HITACHI HD7406P.
ICS703	B19/5ZJAB00028	IC Socket: 28 pins.
ICS704	B19/5ZJAB00033	IC Socket: 8 pins.
----- JACKS -----		
J601 and J602	B19/5JTCAR00137	Connector: 3 pins.
J701	B19/5JJAL000078	Connector: 8 pins.
J702	B19/5JWB800182	Connector: 24 pins.
J703	B19/5JWB800240	Connector: 16 pins.
J704	B19/5JTCAR00288	Connector: 5 pins.
----- COILS -----		
L601	B19/5LCAR00599	Croke coil 20 uH.
----- PLUGS -----		
P601 and P602	B19/5JDAN00012	Short plug: 2 pins.
----- RESISTORS -----		
R601	B19/5RDAC02449	Metal film: 100K ohms ±5%, 100 VDCW, 1/10 w.
R602	B19/5RDAC02446	Metal film: 1K ohms ±5%, 100 VDCW, 1/10 w.
R603	B19/5RDAC02439	Metal film: 47K ohms ±5%, 100 VDCW, 1/10 w.
R604	B19/5RDAC02453	Metal film: 220K ohms ±5%, 100 VDCW, 1/10 w.
R605	B19/5RDAC02454	Metal film: 22K ohms ±5%, 100 VDCW, 1/10 w.
R606	B19/5RDAC02444	Metal film: 56K ohms ±5%, 100 VDCW, 1/10 w.
R607	B19/5RDAC02449	Metal film: 100K ohms ±5%, 100 VDCW, 1/10 w.
R610	B19/5RDAC02463	Metal film: 560K ohms ±5%, 100 VDCW, 1/10 w.
R611	B19/5SREAG03000	Metal film: 634K ohms ±1%, 100 VDCW, 1/10 w.
R612	B19/5SREAG03001	Metal film: 249K ohms ±1%, 100 VDCW, 1/10 w.
R613	B19/5SREAG03002	Metal film: 100K ohms ±1%, 100 VDCW, 1/10 w.
R614	B19/5SREAG03003	Metal film: 40.2K ohms ±1%, 100 VDCW, 1/10 w.
R615	B19/5SREAG03004	Metal film: 15.8K ohms ±1%, 100 VDCW, 1/10 w.
R616	B19/5SREAG03005	Metal film: 6.34K ohms ±1%, 100 VDCW, 1/10 w.
R617	B19/5SREAG03006	Metal film: 2.49K ohms ±1%, 100 VDCW, 1/10 w.
R618	B19/5SREAG03022	Metal film: 931 ohms ±1%, 100 VDCW, 1/10 w.
R623	B19/5SREAG03023	Metal film: 1.5K ohms ±1%, 100 VDCW, 1/10 w.

SYMBOL	PART NO.	DESCRIPTION
R624	B19/5SREAG03007	Metal film: 1K ohms ±1%, 100 VDCW, 1/10 w.
R625	B19/5RDAC02446	Metal film: 1K ohms ±5%, 100 VDCW, 1/10 w.
R627	B19/5RDAC02482	Metal film: 18K ohms ±5%, 100 VDCW, 1/10 w.
R628	B19/5RDAC02453	Metal film: 220K ohms ±5%, 100 VDCW, 1/10 w.
R629	B19/5RZAB01254	Metal film: 91K ohms ±5%, 100 VDCW, 1/10 w.
R630	B19/5RDA01539	Carbon film: 1.2K ohms ±5%, 300 VDCW, 1/4 w.
R631	B19/5RDAC02482	Metal film: 18K ohms ±5%, 100 VDCW, 1/10 w.
R632	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R633	B19/5RDAC02471	Metal film: 470 ohms ±5%, 100 VDCW, 1/10 w.
R634	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R635	B19/5RDAC02486	Metal film: 82K ohms ±5%, 100 VDCW, 1/10 w.
R636	B19/5RDAC02462	Metal film: 3.3K ohms ±5%, 100 VDCW, 1/10 w.
R637	B19/5RDAC02439	Metal film: 47K ohms ±5%, 100 VDCW, 1/10 w.
R638	B19/5RDAC02447	Metal film: 100 ohms ±5%, 100 VDCW, 1/10 w.
R639 and R640	B19/5RDAC02487	Metal film: 120K ohms ±5%, 100 VDCW, 1/10 w.
R641	B19/5RDAC02453	Metal film: 220K ohms ±5%, 100 VDCW, 1/10 w.
R642	B19/5RDAC02463	Metal film: 560K ohms ±5%, 100 VDCW, 1/10 w.
R643	B19/5RDAC02587	Metal film: 820K ohms ±5%, 100 VDCW, 1/10 w.
R644	B19/5RDAC02446	Metal film: 1K ohms ±5%, 100 VDCW, 1/10 w.
R645 and R646	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R647	B19/5RDAC02459	Metal film: 180K ohms ±5%, 100 VDCW, 1/10 w.
R648	B19/5RDAC02457	Metal film: 27K ohms ±5%, 100 VDCW, 1/10 w.
R649	B19/5RDAC02488	Metal film: 270K ohms ±5%, 100 VDCW, 1/10 w.
R651 and R652	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R653	B19/5RDAC02446	Metal film: 1K ohms ±5%, 100 VDCW, 1/10 w.
R657	B19/5RDAC02446	Metal film: 1K ohms ±5%, 100 VDCW, 1/10 w.
R701	B19/5RDAC02447	Metal film: 100 ohms ±5%, 100 VDCW, 1/10 w.
R702	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R703	B19/5RDAC02447	Metal film: 100 ohms ±5%, 100 VDCW, 1/10 w.
R704 thru R707	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R708	B19/5RDAC02451	Metal film: 2.2K ohms ±5%, 100 VDCW, 1/10 w.
R710	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R711	B19/5RDAC02451	Metal film: 2.2K ohms ±5%, 100 VDCW, 1/10 w.
R712	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R713	B19/5RDAC02451	Metal film: 2.2K ohms ±5%, 100 VDCW, 1/10 w.
R714	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R715 thru R722	B19/5RDAC02447	Metal film: 100 ohms ±5%, 100 VDCW, 1/10 w.
R723 thru R727	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R728	B19/5RDAC02439	Metal film: 47K ohms ±5%, 100 VDCW, 1/10 w.
R729	B19/5RDAC02446	Metal film: 1K ohms ±5%, 100 VDCW, 1/10 w.
R730	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R731	B19/5RDAC02477	Metal film: 3.9K ohms ±5%, 100 VDCW, 1/10 w.
R732 thru R734	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R735	B19/5RDAC02477	Metal film: 3.9K ohms ±5%, 100 VDCW, 1/10 w.
R736 thru R746	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R747	B19/5RDAC02581	Metal film: 0 ohms ±5%, 100 VDCW, 1/10 w.
R748	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
RV601	B19/5RVAB00399	Variable: 10K ohms ±30%, 0.1 w.

SYMBOL	PART NO.	DESCRIPTION
----- TRANSISTORS -----		
TR601 thru TR603	B19/5TCAZ00007	Silicon, NPN: sim to SANYO 2SC3396.
TR604	B19/5TDAB00054	Silicon, NPN: sim to NEC 2SD596.
TR605	B19/5TCAZ00007	Silicon, NPN: sim to SANYO 2SC3396.
TR701	B19/5TBAB00055	Silicon, PNP: sim to NEC 2SB624.
TR702	B19/5TCAZ00007	Silicon, NPN: sim to SANYO 2SC3396.
TR703	B19/5TBAB00055	Silicon, PNP: sim to NEC 2SB624.
TR704 thru TR709	B19/5TCAZ00007	Silicon, NPN: sim to SANYO 2SC3396.
TR710	B19/5TBAB00055	Silicon, PNP: sim to NEC 2SB624.
TR711 thru TR717	B19/5TCAZ00007	Silicon, NPN: sim to SANYO 2SC3396.
TR718	B19/5TDAB00054	Silicon, NPN: sim to NEC 2SD596.
TR719	B19/5TBAB00055	Silicon, PNP: sim to NEC 2SB624.
TR720	B19/5TCAZ00007	Silicon, NPN: sim to SANYO 2SC3396.
----- CRYSTALS -----		
X701	B19/5XHAA00817	Quartz crystal: F=8.192 MHz.
X701-1 and X701-2	B19/5ZJDP00001	Crystal Socket.

*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES

PARTS LIST

SYNTHESIZER SECTION
MLS
(LOW BAND)
CMC-551-2
ISSUE 1

SYMBOL	PART NO.	DESCRIPTION
		B19/CMC-551A (29.7-42 MHz) B19/CMC-551B (42-50 MHz)
		----- CAPACITORS -----
C201 and C202	B19/5CAAD01131	Ceramic: 0.047 uF ±10%, 25 VDCW, Temp coef ±10%.
C203	B19/5CEAA01829	Electrolytic: 470 uF ±20%, 16 VDCW.
C204	B19/5CEAA01982	Electrolytic: 47 uF ±20%, 16 VDCW.
C205	B19/5CAAD01131	Ceramic: 0.047 uF ±10%, 25 VDCW, Temp coef ±10%.
C206	B19/5CRAA00628	Metallized Plastic: 0.047 uF ±5%, 50 VDCW.
C207	B19/5CRAA00773	Metallized Plastic: 1 uF ±5%, 50 VDCW.
C208	B19/5CRAA00617	Metallized Plastic: 0.1 uF ±5%, 50 VDCW.
C209	B19/5CAAD00958	Ceramic: 150 pF ±5%, 50 VDCW, Temp coef 0±30 PPM.
C210 and C211	B19/5CAAD00838	Ceramic: 1000 pF ±10%, 50 VDCW, Temp coef ±15%.
C212	B19/5CAAD01131	Ceramic: 0.047 uF ±10%, 25 VDCW, Temp coef ±10%.
C213 thru C217	B19/5CAAD00838	Ceramic: 1000 pF ±10%, 50 VDCW, Temp coef ±15%.
C219	B19/5CAAD00969	Ceramic: 56 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C219	B19/5CAAD00948	Ceramic: 33 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C221	B19/5CAAD00969	Ceramic: 56 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C221	B19/5CAAD00948	Ceramic: 33 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C222	B19/5CAAD00959	Ceramic: 0.01 uF ±10%, 50 VDCW, Temp coef ±15%.
C223 and C224	B19/5CAAD00948	Ceramic: 33 pF ±5%, 50 VDCW, Temp coef 0±30 PPM.
C225	B19/5CAAD00956	Ceramic: 5 pF ±0.25 pF, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C225	B19/5CAAD00853	Ceramic: 3 pF ±0.25 pF, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C226 thru C229	B19/5CAAD00838	Ceramic: 1000 pF ±10%, 50 VDCW, Temp coef ±15%.
C230	B19/5CEAA01827	Electrolytic: 100 uF ±20%, 16 VDCW.
C232	B19/5CAAD00963	Ceramic: 18 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C232	B19/5CAAD00950	Ceramic: 15 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C233	B19/5CAAD00957	Ceramic: 4700 pF ±10%, 50 VDCW, Temp coef ±15%.
C235	B19/5CAAD00960	Ceramic: 82 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C235	B19/5CAAD00948	Ceramic: 33 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C237	B19/5CAAD00958	Ceramic: 150 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C237	B19/5CZAJ00014	Ceramic: 22 pF ±5%, 50 VDCW, Temp coef -750 ±120 pPF. (Used in B).
C238	B19/5CAAD00838	Ceramic: 1000 pF ±10%, 50 VDCW, Temp coef ±15%.
C239	B19/5CAAD00959	Ceramic: 0.01 uF ±10%, 50 VDCW, Temp coef ±15%.
C240	B19/5CAAD00948	Ceramic: 33 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C240	B19/5CAAD00955	Ceramic: 39 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C241	B19/5CAAD00969	Ceramic: 56 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).

*COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES

SYMBOL	PART NO.	DESCRIPTION
C241	B19/5CAAD00854	Ceramic: 47 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C242	B19/5CAAD00953	Ceramic: 10 pF ±0.5 pF, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C242	B19/5CAAD00956	Ceramic: 5 pF ±0.25 pF, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C243 thru C245	B19/5CAAD00838	Ceramic: 1000 pF ±10%, 50 VDCW, Temp coef ±15%.
C247	B19/5CEAA01831	Electrolytic: 1 uF ±20%, 50 VDCW.
C248	B19/5CSAC00939	Tantalum: 22 uF ±20%, 16 VDCW.
C249	B19/5CEAA01829	Electrolytic: 470 uF ±20%, 16 VDCW.
C251	B19/5CAAD00838	Ceramic: 1000 pF ±10%, 50 VDCW, Temp coef ±15%.
C256	B19/5CAAD01131	Ceramic: 0.047 uF ±10%, 25 VDCW, Temp coef ±10%.
C257	B19/5CEAA01982	Electrolytic: 47 uF ±20%, 16 VDCW.
C258	B19/5CRAA00587	Polyester: 0.01 uF ±5%, 50 VDCW.
C259	B19/5CEAA01982	Electrolytic: 47 uF ±20%, 16 VDCW.
C260	B19/5CRAA00617	Metallized Plastic: 0.1 uF ±5%, 50 VDCW.
C261	B19/5CEAA01982	Electrolytic: 47 uF ±20%, 16 VDCW.
C262 and C263	B19/5CEAA01864	Electrolytic: 10 uF ±20%, 16 VDCW.
C264	B19/5CRAA00587	Polyester: 0.01 uF ±5%, 50 VDCW.
C265	B19/5CRAA00585	Polyester: 1000 pF ±5%, 50 VDCW.
C266	B19/5CAAD00948	Ceramic: 33 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C266	B19/5CAAD00963	Ceramic: 18 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in B).
C267 and C268	B19/5CAAD00838	Ceramic: 1000 pF ±10%, 50 VDCW, Temp coef ±15%.
C273 thru C275	B19/5CAAD00838	Ceramic: 1000 pF ±10%, 50 VDCW, Temp coef ±15%.
C282	B19/5CAAD00974	Ceramic: 390 pF ±5%, 50 VDCW, Temp coef 0±30 PPM.
C283	B19/5CSAC01486	Tantalum: 3.3 uF ±10%, 16 VDCW.
C284	B19/5CRAA00838	Metallized Plastic: 0.47 uF ±5%, 50 VDCW.
C285 and C286	B19/5CEAA01827	Electrolytic: 100 uF ±20%, 16 VDCW.
C292	B19/5CAAD00952	Ceramic: 27 pF ±5%, 50 VDCW, Temp coef 0±30 PPM. (Used in A).
C293	B19/5CAAD00952	Ceramic: 27 pF ±5%, 50 VDCW, Temp coef 0±30 PPM.
C296 and C297	B19/5CAAD00952	Ceramic: 27 pF ±5%, 50 VDCW, Temp coef 0±30 PPM.
CV201	B19/5CVAR00193	Variable: 50 pF max. (Used in A).
CV201	B19/5CVAR00106	Variable: 30 pF max. (Used in B).
		----- DIODES -----
CD201	B19/5TXAE00587	Zener: 4V; sim to HITACHI HZ4B3.
CD202	B19/5TXAE00566	Zener: 3V; sim to HITACHI HZ3B2.
CD203	B19/5TXAT00004	Silicon, Fast Recovery, (RF switch): sim to MITSUBISHI M1301.
CD204	B19/5TXAD00320	Silicon, Fast Recovery (2 diodes in series): sim to TOSHIBA 1SS226.
CD205	B19/5TXAR00326	Silicon: Schottky Barrier; sim to NEC 1SS97.
CD206	B19/5TXAE00566	Zener: 3V; sim to HITACHI HZ3B2.
CD207	B19/5TXAE00690	Silicon, Variable Capacitance Diode: sim to HITACHI LSV126.
CD208	B19/5TXAT00004	Silicon, Fast Recovery, (RF switch): sim to MITSUBISHI M1301.
CD210	B19/5TXAR00326	Silicon: Schottky Barrier; sim to NEC 1SS97.
CD211	B19/5TXAE00566	Zener: 3V; sim to HITACHI HZ3B2.
CD213 and CD214	B19/5TXAD00320	Silicon, Fast Recovery (2 diodes in series): sim to TOSHIBA 1SS226.

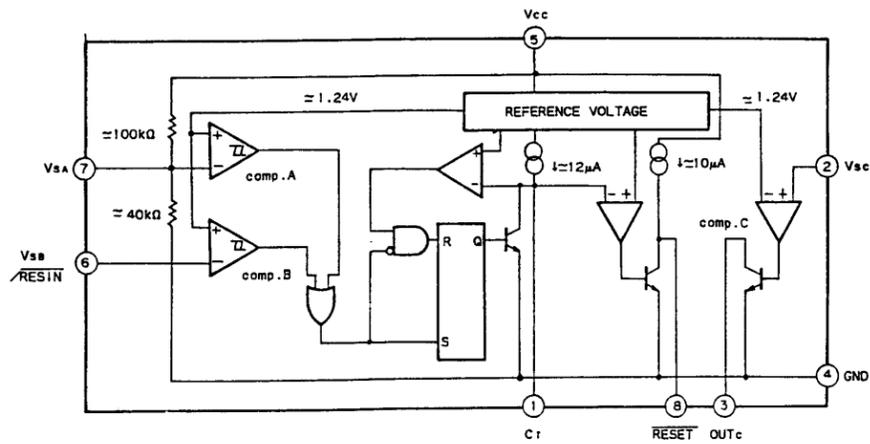
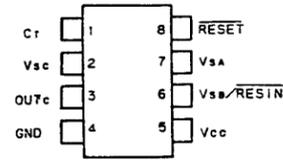
SYMBOL	PART NO.	DESCRIPTION
		----- INTEGRATED CIRCUITS -----
IC201	B19/5DAAJ00328	Synthesizer: CMOS Serial Input: sim to MOTOROLA MC145159P.
IC202	B19/5DDAT00206	Prescaler: sim to FUJITSU MB501P.
IC203	B19/5DAAJ00629	Digital Bilateral Switch: sim to MOTOROLA MC14066 BFP.
IC204 thru IC206	B19/5DAAA00284	RF Wide-band amplifier: sim to NEC UPCL676G.
IC207	B19/5DAAR00021	Linear, Positive Voltage Regulator: sim to MATSUSHITA AN6541.
IC208	B19/5DAAN00365	Linear, Dual OP Amp; sim to New JRC NJM4558M.
IC209	B19/5DAAA00183	RF wide-band amplifier: sim to NEC UPCL656C.
IC210	B19/5DDBA00367	Linear, Dual OP Amp; sim to MITSUBISHI M5223FP.
		----- CONNECTORS -----
J201	B19/5JNCL00058	Connector, RF.
		----- COILS -----
L201	B19/5LCAA00114	Choke Coil: 10 uH ±10%.
L202	B19/6LALD00001	Coil, RF.
L204	B19/5LCAA00114	Choke Coil: 10 uH ±10%.
L205	B19/5LCAA00114	Choke Coil: 10 uH ±10%. (Used in A).
L205	B19/5LCAA00317	Choke Coil: 4.7 uH ±10%. (Used in B).
L206	B19/6LALD00002	Coil, RF. (Used in A).
L206	B19/6LALD00004	Coil, RF. (Used in B).
L208	B19/5LCAA00114	Choke Coil: 10 uH ±10%. (Used in A).
L208	B19/5LCAA00115	Choke Coil: 1 uH ±10%. (Used in B).
L210	B19/6LALD00005	Coil, RF. (Used in A).
L210	B19/6LALD00006	Coil, RF. (Used in B).
		----- RESISTORS -----
R201	B19/5RDAC02465	Metal film: 22 ohms ±5%, 100 VDCW, 1/10 w.
R204	B19/5RDA01480	Carbon film: 330 ohms ±5%, 300 VDCW, 1/4 w.
R205	B19/5RDAC02449	Metal film: 100 ohms ±5%, 100 VDCW, 1/10 w.
R206	B19/5RDAC02458	Metal film: 6.8K ohms ±5%, 100 VDCW, 1/10 w.
R207	B19/5RDAC02462	Metal film: 3.3K ohms ±5%, 100 VDCW, 1/10 w.
R209	B19/5RDAC02453	Metal film: 220K ohms ±5%, 100 VDCW, 1/10 w.
R210	B19/5RDAC02485	Metal film: 68K ohms ±5%, 100 VDCW, 1/10 w. (Used in A).
R210	B19/5RDAC02480	Metal film: 12K ohms ±5%, 100 VDCW, 1/10 w. (Used in B).
R211	B19/5RDAC02487	Metal film: 120K ohms ±5%, 100 VDCW, 1/10 w.
R212	B19/5RDAC02451	Metal film: 2.2K ohms ±5%, 100 VDCW, 1/10 w.
R213 and R214	B19/5RDAC02445	Metal film: 10K ohms ±5%, 100 VDCW, 1/10 w.
R219	B19/5RDAC02439	Metal film: 47K ohms ±5%, 100 VDCW, 1/10 w.
R221	B19/5RDAC02467	Metal film: 68 ohms ±5%, 100 VDCW, 1/10 w.
R222	B19/5RDAC02460	Metal film: 47 ohms ±5%, 100 VDCW, 1/10 w.
R223	B19/5RDAC02554	Metal film: 120 ohms ±5%, 100 VDCW, 1/10 w. (Used in A).
R223	B19/5RDAC02468	Metal film: 150 ohms ±5%, 100 VDCW, 1/10 w. (Used in B).
R224	B19/5RDAC02460	Metal film: 47 ohms ±5%, 100 VDCW, 1/10 w. (Used in A).
R224	B19/5RDAC02466	Metal film: 33 ohms ±5%, 100 VDCW, 1/10 w. (Used in B).
R225	B19/5RDAC02554	Metal film: 120 ohms ±5%, 100 VDCW, 1/10 w. (Used in A).
R225	B19/5RDAC02468	Metal film: 150 ohms ±5%, 100 VDCW, 1/10 w. (Used in B).
R226	B19/5RDAC02581	Metal film: 0 ohms. (Used in A).
R226	B19/5RDAC02478	Metal film: 4.7K ohms ±5%, 100 VDCW, 1/10 w. (Used in B).

PARTS LIST

SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION
R227	B19/5RDAC02449	Metal film: 100K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R228	B19/5RDAC02454	Metal film: 22K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R229	B19/5RDAC02462	Metal film: 3.3K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R230	B19/5RDAC02439	Metal film: 47K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R231	B19/5RDAC02467	Metal film: 68 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R232	B19/5RDAC02460	Metal film: 47 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R233	B19/5RDAC02554	Metal film: 120 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R234	B19/5RDAC02470	Metal film: 330 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R235	B19/5RDAC02554	Metal film: 120 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R236	B19/5RDAC02470	Metal film: 330 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R240 and R241	B19/5RDAC02472	Metal film: 680 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R242	B19/5RDAC02474	Metal film: 1.5K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R243	B19/5RDAC02488	Metal film: 270K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R244	B19/5RDAC02447	Metal film: 100 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R245	B19/5RDAC02478	Metal film: 4.7K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R246	B19/5RDAC02452	Metal film: 5.6K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R248	B19/5RDAC02473	Metal film: 1.2K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R249	B19/5RDAC02446	Metal film: 1K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R250	B19/5RDAC02482	Metal film: 18K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R251	B19/5RDAC02457	Metal film: 27K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R252	B19/5RDAC02445	Metal film: 10K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R253	B19/5RDAC02473	Metal film: 1.2K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R254	B19/5RDAC02439	Metal film: 47K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R255	B19/5RDAC02445	Metal film: 10K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R256	B19/5RDAC02483	Metal film: 33K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R257	B19/5RDAC02449	Metal film: 100K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R259	B19/5RDAC02581	Metal film: 0 ohms. (Used in A).			
R259	B19/5RDAC02466	Metal film: 33 ohms $\pm 5\%$, 100 VDCW, 1/10 w. (Used in B).			
R260 and R261	B19/5RDAC02445	Metal film: 10K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R262	B19/5RDAC02451	Metal film: 2.2K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R263	B19/5RDAC02582	Metal film: 82 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R264	B19/5RDAC02467	Metal film: 68 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R265	B19/5RDAC02471	Metal film: 470 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R266	B19/5RDAC02467	Metal film: 68 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R268	B19/5RDAC02471	Metal film: 470 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R270	B19/5RDAC02470	Metal film: 330 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R271	B19/5RDAC02464	Metal film: 15 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R272	B19/5RDAC02470	Metal film: 330 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R275	B19/5RDAC02445	Metal film: 10K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R276	B19/5RDAC02446	Metal film: 1K ohms $\pm 5\%$, 100 VDCW, 1/10 w. (Used in A).			
R276	B19/5RDAC02581	Metal film: 0 ohms. (Used in B).			
R277	B19/5RDAC02444	Metal film: 56K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R278	B19/5RDAC02461	Metal film: 1M ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R279 and R280	B19/5RDAC02451	Metal film: 2.2K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R281	B19/5RDAC02447	Metal film: 100 ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R282 thru R285	B19/5RDAC02449	Metal film: 100K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R287	B19/5RDAC02445	Metal film: 10K ohms $\pm 5\%$, 100 VDCW, 1/10 w.			
R749	B19/5RDAA01146	Carbon Film: 10K ohm.			
RV201 thru RV203	B19/5RVAB00411	Variable: 10K ohms $\pm 30\%$, 0.1 w.			
					----- TRANSISTORS -----
			TR202	B19/5TBAB00055	Silicon, PNP: sim to NEC 2SB624 (BV3).
			TR205	B19/5TBAB00055	Silicon, PNP: sim to NEC 2SB624 (BV3).
			TR206	B19/5TKAH00006	N-Channel, Field Effect. (Junction Single Gate): sim to SONY 2SK125.
			TR207	B19/5TCAZ00011	Silicon, NPN: sim to SANYO 2SC3398.
			TR209	B19/5TKAH00006	N-Channel, Field Effect. (Junction Single Gate): sim to SONY 2SK125.
			TR210 and TR211	B19/5TDAB00054	Silicon, NPN: sim to NEC 2SD596 (DV3).
			TR215	B19/5TDAB00054	Silicon, NPN: sim to NEC 2SD596 (DV3).
			TR216	B19/5TCAZ00011	Silicon, NPN: sim to SANYO 2SC3398.
					----- CRYSTALS -----
			XU201	B19/6XNFD00017	Reference Oscillator Unit.

RESET CIRCUIT
(IC609) MB3771

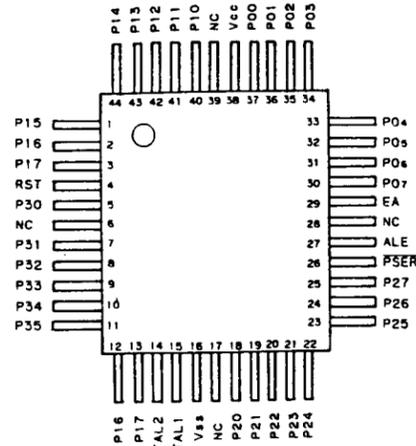
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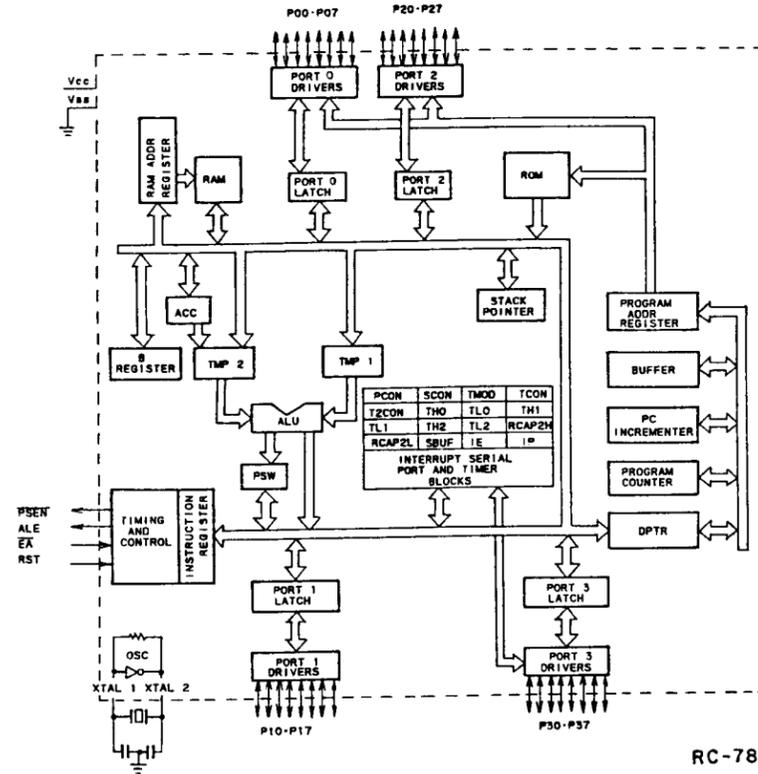
RC-7851

MICROPROCESSOR
(IC701) F-80C32

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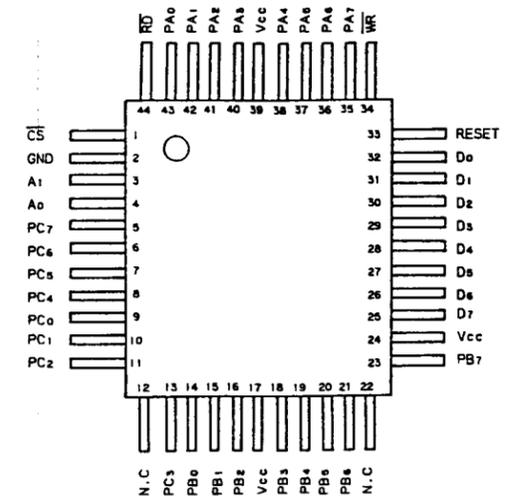
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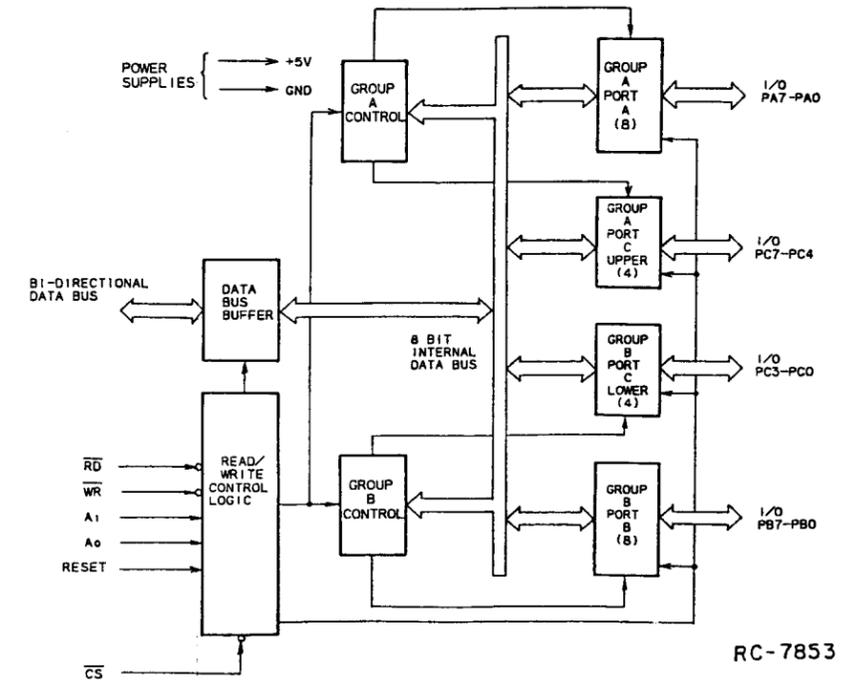
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PROGRAMMABLE PERIPHERAL INTERFACES
(IC705) MSM82C55A 1

PIN CONFIGURATION



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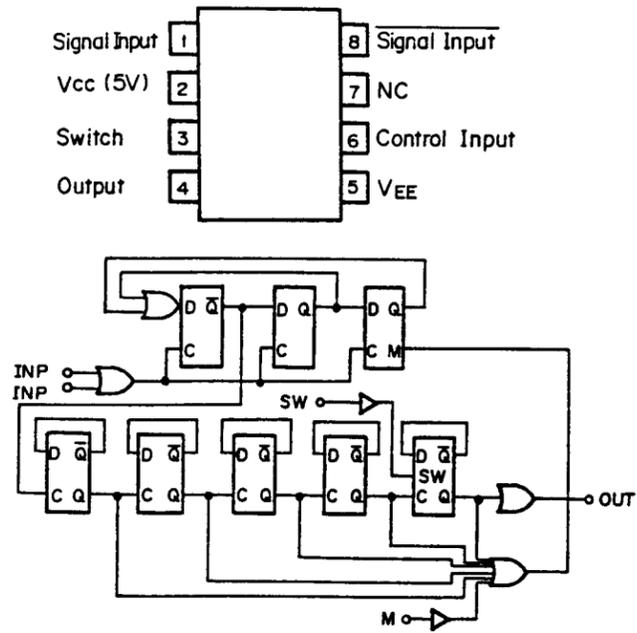


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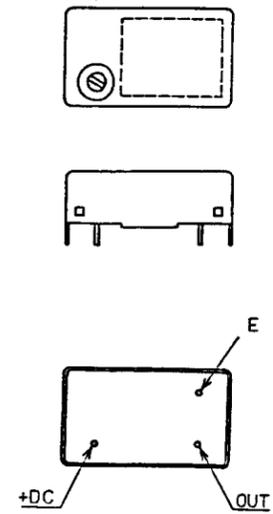
CAUTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
SENSITIVE
DEVICES

DUAL MODULUS
(Prescaler)
IC202



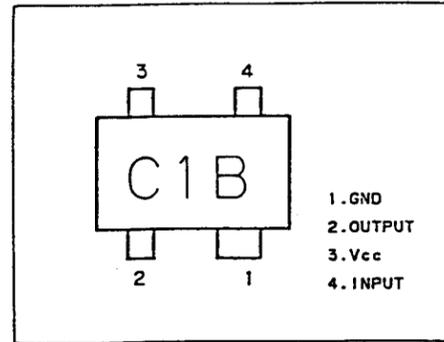
RC-5636A

REFERENCE OSCILLATOR UNIT
XU201



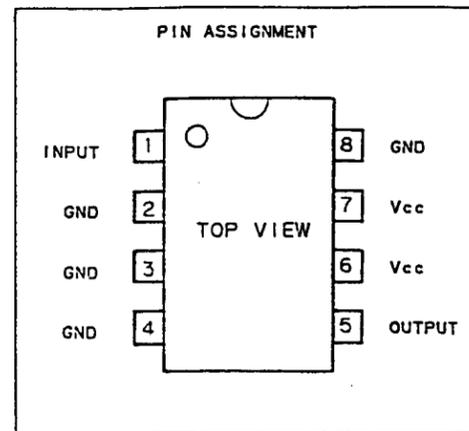
RC-7852

OPERATIONAL AMPLIFIER
(IC204 THROUGH IC206)



RC-7849

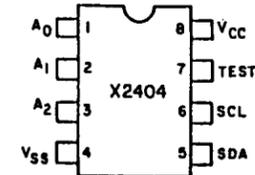
OPERATIONAL AMPLIFIER
(IC209)



RC-7850

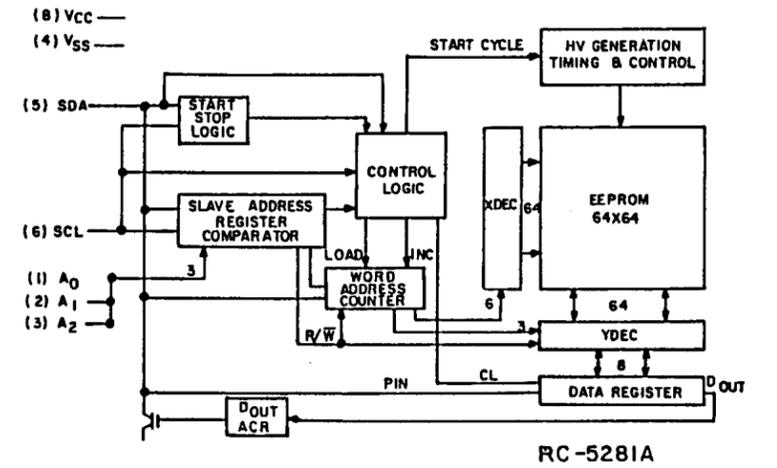
NEC UPC1676G

PIN CONFIGURATION



DIGITAL 512 X 8 EEPROM
(IC704)

FUNCTION DIAGRAM



RC-5281A

NEC UPC1656C



CAUTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
SENSITIVE
DEVICES

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